

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In the application of: Eldridge et al. Application No.: Unknown Filing Date: December 27, 2001 For: PROBE CARD ASSEMBLY AND KIT, AND METHODS OF USING SAME	Examiner: Unknown Group Art Unit: Unknown
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**PRELIMINARY AMENDMENT**

Box: New Application  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Prior to examination of the above-identified patent application (which is filed herewith), please amend the application as follows:

In The Claims

~~Please~~ cancel claim 1 without prejudice.

~~Please~~ add new claims 43-85 as follows:

① 43. (New) A method of producing a tested semiconductor device comprising:

providing a probe card assembly, said probe card assembly including a probe card having a plurality of electrical contacts, a probe substrate having a plurality of elongate, resilient probe elements, and a compliant interconnection structure electrically connecting ones of said electrical contacts with ones of said probe elements;

providing a plurality of semiconductor devices, each of said semiconductor devices including electrical contact pads;

bringing said probe elements into contact with said electrical contact pads of said semiconductor device; and

testing said semiconductor devices.